EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	57	inspect$3 and formation adj state and (wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:27
L2	2	L1 and inspect$3 adj data and pattern adj area and inside and outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:29
L3	1	L2 and inside adj area and perform$3 and reduction	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:31
L5	1	L3 and outside adj area and perform $3 and expansion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:32
L6	0	L5 and(@ad<"20031222" or @rlad<"20031222" or @prad<"20031222" or @ptad<"20031222")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:32
L7	1307	pattern adj inspect$3 and(inside or outside)and(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:34
L8	2	L7 and inside adj area and perform$3 and reduction	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:34
L9	4	L7 and outside adj area and perform $3 and expansion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:34
L10	0	L8 and outside adj area and perform $3 and expansion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:35

L11	4	L9 and(@ad<"20031222" or @rlad<"20031222" or @prad<"20031222" or @ptad<"20031222")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:36
L12	2	L9 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:36
L13	0	L7 and L9 and L8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:46
L14	4	L7 and L9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:46
L15	0	L14 and inside adj area and perform $3 and reduction	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:47
L16	2	L8 and(@ad<"20031222" or @rlad<"20031222" or @prad<"20031222" or @ptad<"20031222")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:48
L17	2	L8 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 10:48
L18	2	"20070147676"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/18 11:13
S1	92648	inspect$3 and(wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:49
S2	57	inspect$3 and formation adj state and (wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:50

S3	45	S2 and(@ad<"20031222" or @rlad<"20031222" or @prad<"20031222" or @ptad<"20031222")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:54
S4	39	S2 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:54
S5	0	S4 and generat$3 and inspect$3 adj data same pattern adj area same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:56
S6	2	inspect$3 adj data same pattern adj area same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:57
S7	39	S4 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:57
S8	0	S7 and inspect$3 adj data same pattern adj area same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:58
S9	0	S7 and inspect$3 adj data and pattern adj area and inside and outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:58
S10	4	S7 and inspect$3 and pattern adj area and inside and outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:59
S11	4	S10 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 11:59
S12	4	S11 and inside and outside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:03
S13	4	S11 and inside and outside and pattern adj(area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:04

S14	4	S11 and inside and outside and pattern adj(area or regions)and (comapar$5 or match$ or combining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:05
S15	4	S11 and inside and outside and pattern adj(area or regions)and (comapar$5 or match$ or combining) and(difference or differ or sum)and (luminance or shapes)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:07
S16	109	("5723236" "4783826" "5608816" "5892224" "5917590" "6166808" "4319270" "4760265" "4897795" "4943186" "5324568" "5331432" "5362591" "5404410" "5621825" "5656397" "5659172" "5665645" "5691543" "5838433" "5885735" "6038015" "6043870" "6052170" "6219807" "6219807" "3806015" "4056716" "4156231" "4244650" "4247748" "4255055" "4270863" "4286266" "4286146" "4295200" "4296474" "4297818" "4311267" "4318590" "4319269" "4320567" "4321534" "4330775" "4339952" "4344146" "4357540" "4365163" "4366564" "4396509").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:20
S17	0	S16 and inspect$3 and formation adj state and(wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:23
S18	0	S16 and inspect$3 adj data same pattern adj area same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:24
S19	22	S16 and inspect$3 and(wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:25
S20	22	S19 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:25

S21	92648	inspect$3 and(wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:50
S22	2	S21 and(generat$3 or obtaining)and inspect$3 adj data same pattern adj area same inside adj pattern same outside adj pattern and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:52
S23	2	S21 and(generat$3 or obtaining)and inspect$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:53
S24	2	(generat$3 or obtaining)and inspect$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:53
S25	20	(generat$3 or obtaining)and inspect$3 and(region or area)adj pattern and inside adj pattern and outside adj pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:55
S26	14	S25 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 12:55
S27	0	S7 and inspect$3 adj data same pattern adj area same object same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:19
S28	0	S25 and inspect$3 adj data same pattern adj area same object same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:19
S29	1	S25 and inspect$3 adj data and pattern adj area and(object or patterns)same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:20
S30	0	S29 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:20
S31	5	S1 and inspect$3 adj data and pattern adj area and(object or patterns)same inside same outside and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:21

S32	3	S31 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:21
S33	12243	430/5,322.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:43
S34	5206	430/5,322.CCLS.	USPAT	OR	ON	2009/04/20 13:44
S35	505	S34 and inspect$3 and(wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	USPAT	OR	ON	2009/04/20 13:44
S36	0	S35 and(generat$3 or obtaining)and inspect$3 and(region or area)adj pattern and inside adj pattern and outside adj pattern	USPAT	OR	ON	2009/04/20 13:45
S37	29	S35 and inspect$3 and pattern adj area and inside and outside and inspect$3	USPAT	OR	ON	2009/04/20 13:47
S38	5	S37 and inside and outside and pattern adj(area or regions)and (comapar$5 or match$ or combining)	USPAT	OR	ON	2009/04/20 13:48
S39	5	S38 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:48
S40	2132	382/149,209,141,147,149..CCLS.	USPAT	OR	ON	2009/04/20 13:50
S41	2132	382/149,209,141,147,149.CCLS.	USPAT	OR	ON	2009/04/20 13:50
S42	508	S41 and inspect$3 and(wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adh pads)	USPAT	OR	ON	2009/04/20 13:51
S43	0	S42 and(generat$3 or obtaining)and inspect$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:51
S44	49494	inspect$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:53

S45	17	S44 and inspect$3 adj data and pattern adj area and(object or patterns or pads or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:54
S46	11	S45 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:55
S47	24563	inspect$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	USPAT	OR	ON	2009/04/20 13:57
S48	2	"chawan_sheela." "XA."	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 13:58
S49	1651	chawan sheela.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:03
S50	1859	chawan sheela.xp.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:03
S51	53	S49 and inspect$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	USPAT	OR	ON	2009/04/20 14:06
S52	54	S49 and inspect$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:06
S53	49	S50 and inspect$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:06
S54	0	S52 and(generat$3 or obtaining)and inspect$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:07
S55	0	S53 and(generat$3 or obtaining)and inspect$3 adj data and pattern adj area and inside adj pattern and outside adj pattern and inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:07
S56	47	S52 and @ad< "20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:08

S57	44	S53 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:08
S58	1	S23 and inspect$3 and(PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:53
S59	55	inspect$3 and formation adj state and (wafer$l or semicondudor$l or chip$l or subtrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board or solder adj joints or pads or solder adj pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:55
S60	1	S59 and inspect$3 adj data same (inside or interior)same luminance same (exterior or outside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:58
S61	38	S59 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:58
S62	0	S61 and inspect$3 adj data same (inside or interior)same luminance same (exterior or outside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 14:58
S63	0	S61 and inspect$3 adj data and measuring and(inside or interior)and luminance and shape and(exterior or outside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:00
S64	2	pattern adj inspect$3 same(inside or exterior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:17
S65	2	S64 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:18
S66	0	S65 and pattern adj inspect$3 same (outside or exterior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:19
S67	2	pattern adj inspect$3 same(inside or interior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:19

S68	0	S67 and pattern adj inspect$3 same (outside or exterior)adj(area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:20
S69	3	S2 and(generat$3 or obtaining)and inspect$3 adj data and pattern adj (area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:30
S70	0	S69 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:31
S71	0	S2 and(generat$3 or obtaining)and inspect$3 adj data and pattern adj (area or region)and difference adj image$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:33
S72	37	(generat$3 or obtaining)and inspect $3 adj data and pattern adj(area or region)and difference adj image$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:33
S73	25	S72 and pattern adj inspect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:33
S74	21	S73 and (outline or edge or countour)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:34
S75	0	S74 and inspect$3 adj data same luminance same shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:48
S76	2	S74 and inspect$3 adj data and luminance and shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:49
S77	2	S76 and @ad<"20031222"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 15:49
S78	2	"6327379".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/20 16:51

| S79 | 2 | S78 and @ad< "20031222" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/04/20 16:51 |
| S80 | 0 | S79 and difference | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/04/20 16:53 |

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L23	1	(inspect$3 adj data and pattern adj area and inside and outside and inspect$3).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2009/09/18 11:25

9/18/09 11:29:27 AM
C:\ Documents and Settings\ SChawan\ My Documents\ EAST\ Workspaces\ 3660.wsp